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[74ACT11374DW](#)

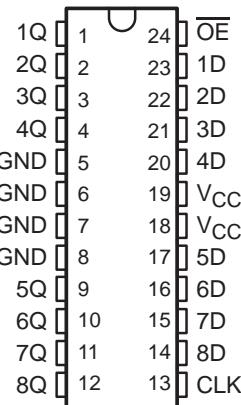
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74ACT11374
OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP
WITH 3-STATE OUTPUTS
 SCAS217A – JULY 1987 – REVISED APRIL 1996

- Eight D-Type Flip-Flops in a Single Package
- 3-State Bus Driving True Outputs
- Full Parallel Access for Loading
- Inputs Are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- **EPIC™** (Enhanced-Performance Implanted CMOS) 1- μ m Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, and Standard Plastic 300-mil DIPs (NT)

DB, DW, OR NT PACKAGE
 (TOP VIEW)



description

This 8-bit flip-flop features 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 74ACT11374 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

An output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance third state provides the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

\overline{OE} does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT11374 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE
 (each flip-flop)

| INPUTS | | | OUTPUT Q |
|-----------------|-----|---|-------------|
| \overline{OE} | CLK | D | |
| L | ↑ | H | H |
| L | ↑ | L | L |
| L | L | X | Q_0 |
| L | H | X | Q_0 |
| L | ↓ | X | Q_0 |
| H | X | X | Z |



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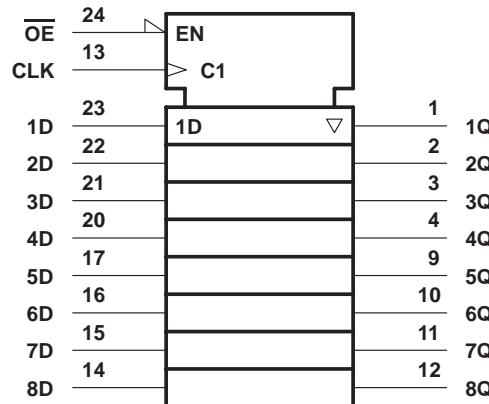
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74ACT11374

**OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP
WITH 3-STATE OUTPUTS**

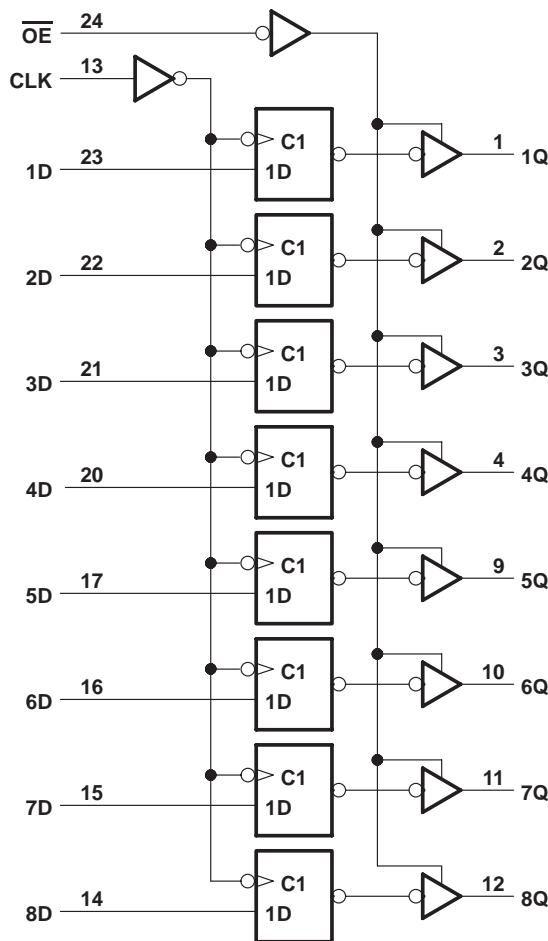
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | | |
|---|----------------------------|-------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V | |
| Input voltage range, V_I (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V | |
| Output voltage range, V_O (see Note 1) | -0.5 V to $V_{CC} + 0.5$ V | |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) | ± 20 mA | |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ± 50 mA | |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 50 mA | |
| Continuous current through V_{CC} or GND | ± 200 mA | |
| Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DB package | 0.65 W | |
| | DW package | 1.7 W |
| | NT package | 1.3 W |
| Storage temperature range, T_{stq} | -65°C to 150°C | |

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero.

recommended operating conditions

| | | MIN | MAX | UNIT |
|---------------------|------------------------------------|-----|----------|------|
| V_{CC} | Supply voltage | 4.5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | V |
| V_{IL} | Low-level input voltage | | 0.8 | V |
| V_I | Input voltage | 0 | V_{CC} | V |
| V_O | Output voltage | 0 | V_{CC} | V |
| I_{OH} | High-level output current | | -24 | mA |
| I_{OL} | Low-level output current | | 24 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | 0 | 10 | ns/V |
| T_A | Operating free-air temperature | -40 | 85 | °C |

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OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | MIN | MAX | UNIT |
|-------------------------------|---|-----------------|-----------------------|------|------|-----|-----|------|
| | | | MIN | TYP | MAX | | | |
| V _{OH} | I _{OH} = -50 µA | 4.5 V | 4.4 | | 4.4 | V | 5.4 | V |
| | | 5.5 V | 5.4 | | 5.4 | | | |
| | I _{OH} = -24 mA | 4.5 V | 3.94 | | 3.8 | | | |
| | | 5.5 V | 4.94 | | 4.8 | | | |
| | I _{OH} = -75 mA [†] | 5.5 V | | | 3.85 | | | |
| | | | | | | | | |
| V _{OL} | I _{OL} = 50 µA | 4.5 V | | 0.1 | 0.1 | V | 0.1 | V |
| | | 5.5 V | | 0.1 | 0.1 | | | |
| | I _{OL} = 24 mA | 4.5 V | | 0.36 | 0.44 | | | |
| | | 5.5 V | | 0.36 | 0.44 | | | |
| | I _{OL} = 75 mA [†] | 5.5 V | | | 1.65 | | | |
| | | | | | | | | |
| I _{OZ} | V _O = V _{CC} or GND | 5.5 V | | ±0.5 | ±5 | µA | | |
| I _I | V _I = V _{CC} or GND | 5.5 V | | ±0.1 | ±1 | µA | | |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | 8 | 80 | µA | | |
| ΔI _{CC} [‡] | One input at 3.4 V, Other inputs at GND or V _{CC} | 5.5 V | | 0.9 | 1 | mA | | |
| C _i | V _I = V _{CC} or GND | 5 V | | 4 | | pF | | |
| C _o | V _O = V _{CC} or GND | 5 V | | 10 | | pF | | |

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended ranges of supply voltages and operating free-air temperature (unless otherwise noted) (see Figure 1)

| | | T _A = 25°C | | MIN | MAX | UNIT |
|--------------------|--|-----------------------|-----|-----|-----|------|
| | | MIN | MAX | | | |
| f _{clock} | Clock frequency | 0 | 55 | 0 | 55 | MHz |
| t _w | Pulse duration, CLK low or CLK high | 9 | | 9 | | ns |
| t _{su} | Setup time, data before CLK [†] | 3 | | 3 | | ns |
| t _h | Hold time, data after CLK [†] | 5.5 | | 5.5 | | ns |

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

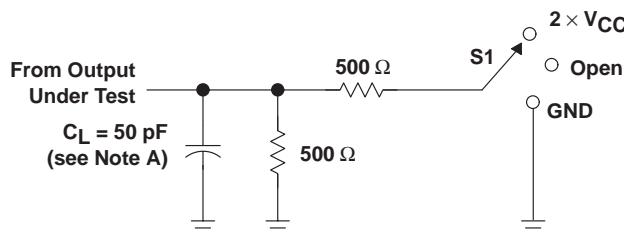
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | T _A = 25°C | | | MIN | MAX | UNIT |
|------------------|--------------|-------------|-----------------------|-----|------|-----|------|------|
| | | | MIN | TYP | MAX | | | |
| f _{max} | | | 55 | 70 | | 55 | | MHz |
| t _{PLH} | CLK | Any Q | 1.5 | 8.5 | 10.7 | 1.5 | 12.4 | ns |
| t _{PHL} | | | 1.5 | 8.5 | 11.3 | 1.5 | 13 | |
| t _{PZH} | OE | Any Q | 1.5 | 7.5 | 11 | 1.5 | 12.3 | ns |
| t _{PZL} | | | 1.5 | 7.5 | 11 | 1.5 | 12.3 | |
| t _{PHZ} | OE | Any Q | 1.5 | 11 | 12.7 | 1.5 | 13.2 | ns |
| t _{PLZ} | | | 1.5 | 8 | 10 | 1.5 | 10.8 | |

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operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$

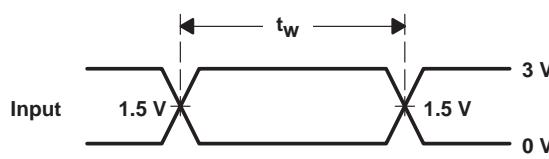
| PARAMETER | | TEST CONDITIONS | TYP | UNIT |
|-----------|---|------------------|-----|------|
| C_{pd} | Power dissipation capacitance per flip-flop | Outputs enabled | 107 | |
| | | Outputs disabled | 96 | pF |

PARAMETER MEASUREMENT INFORMATION

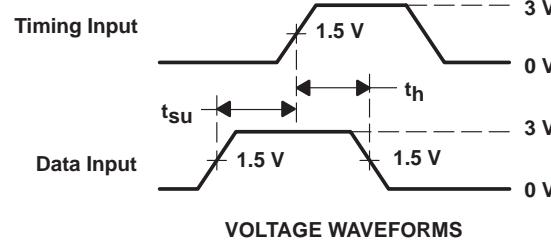


| TEST | S1 |
|-------------------|-------------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | $2 \times V_{CC}$ |
| t_{PHZ}/t_{PZH} | GND |

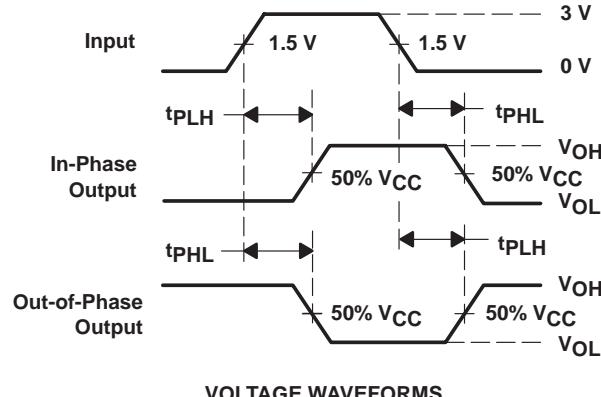
LOAD CIRCUIT



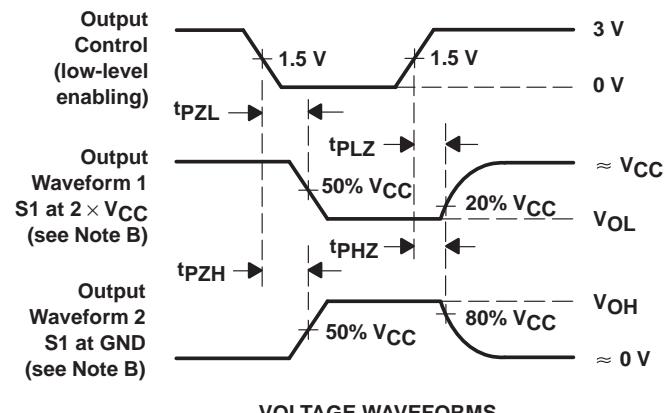
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 74ACT11374DBLE | OBsolete | SSOP | DB | 24 | | TBD | Call TI | Call TI |
| 74ACT11374DW | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ACT11374DWE4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ACT11374DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ACT11374DWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ACT11374DWRE4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ACT11374DWRG4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 74ACT11374NT | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| 74ACT11374NTE4 | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

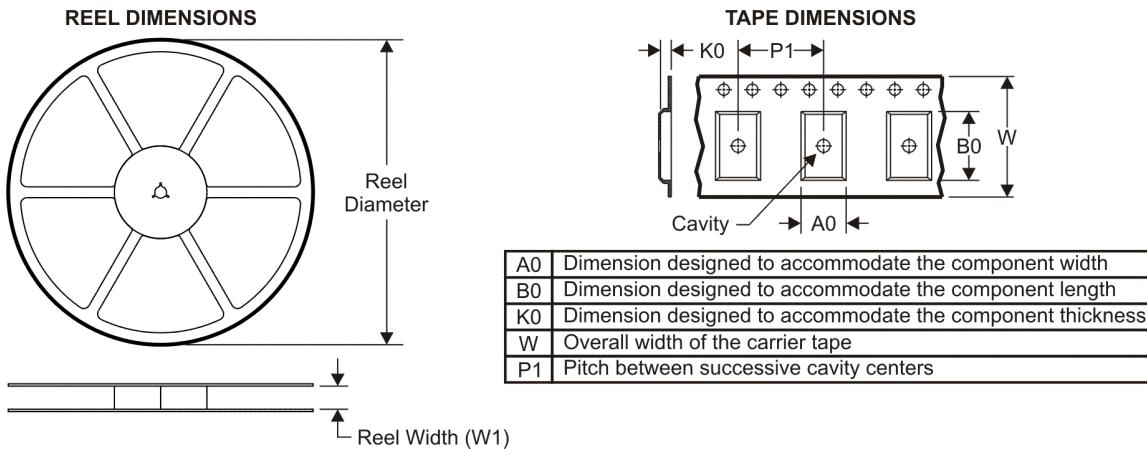
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

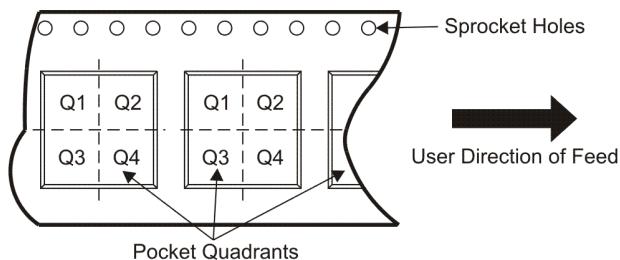
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TAPE AND REEL INFORMATION



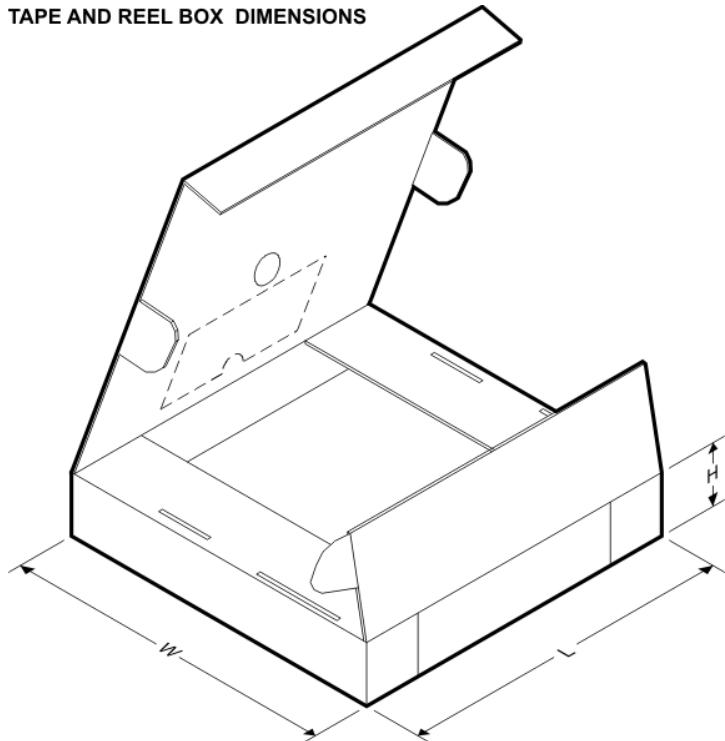
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| 74ACT11374DWR | SOIC | DW | 24 | 2000 | 330.0 | 24.4 | 10.75 | 15.7 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

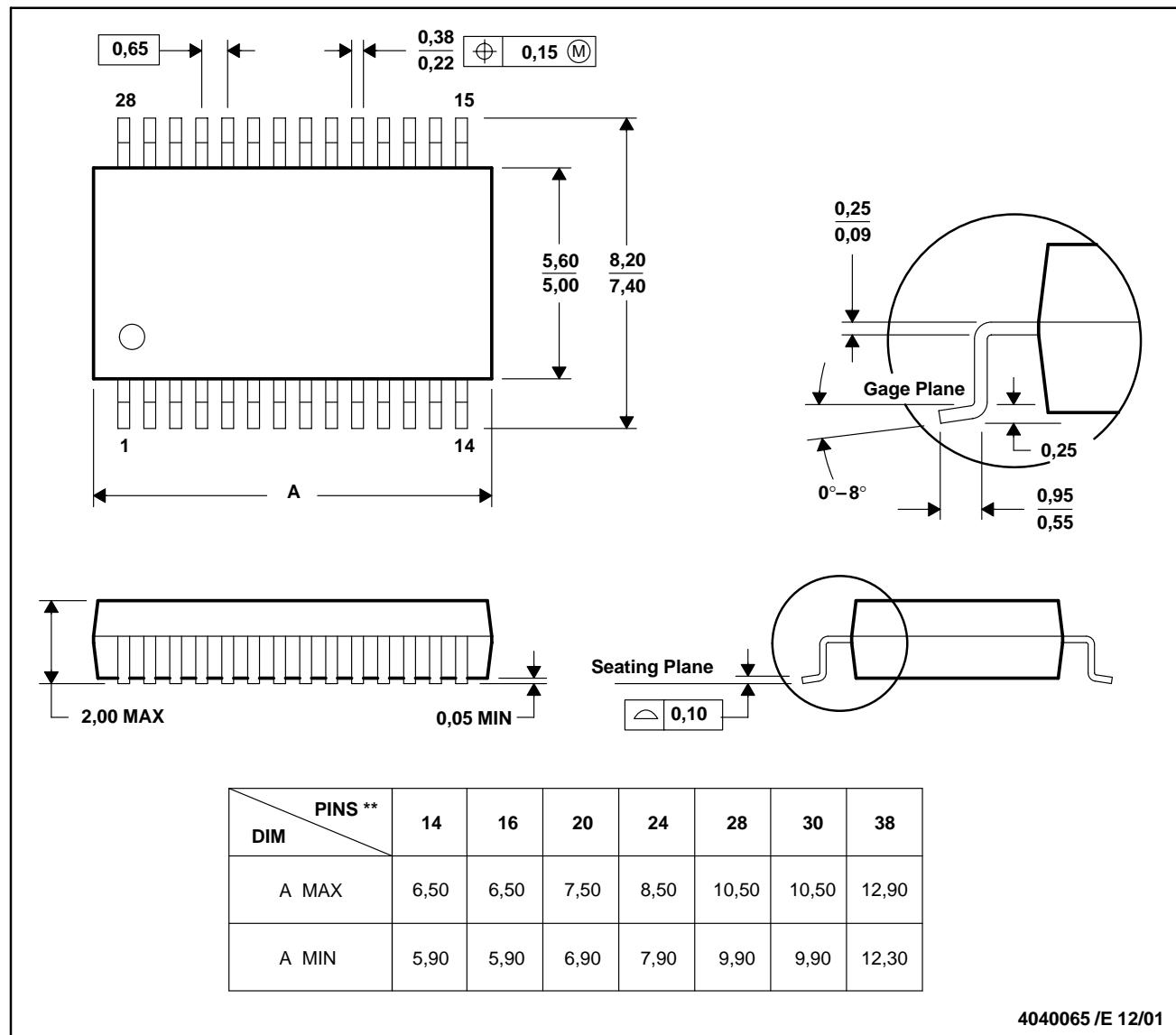
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| 74ACT11374DWR | SOIC | DW | 24 | 2000 | 346.0 | 346.0 | 41.0 |

MSS002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)**

28 PINS SHOWN

PLASTIC SMALL-OUTLINE



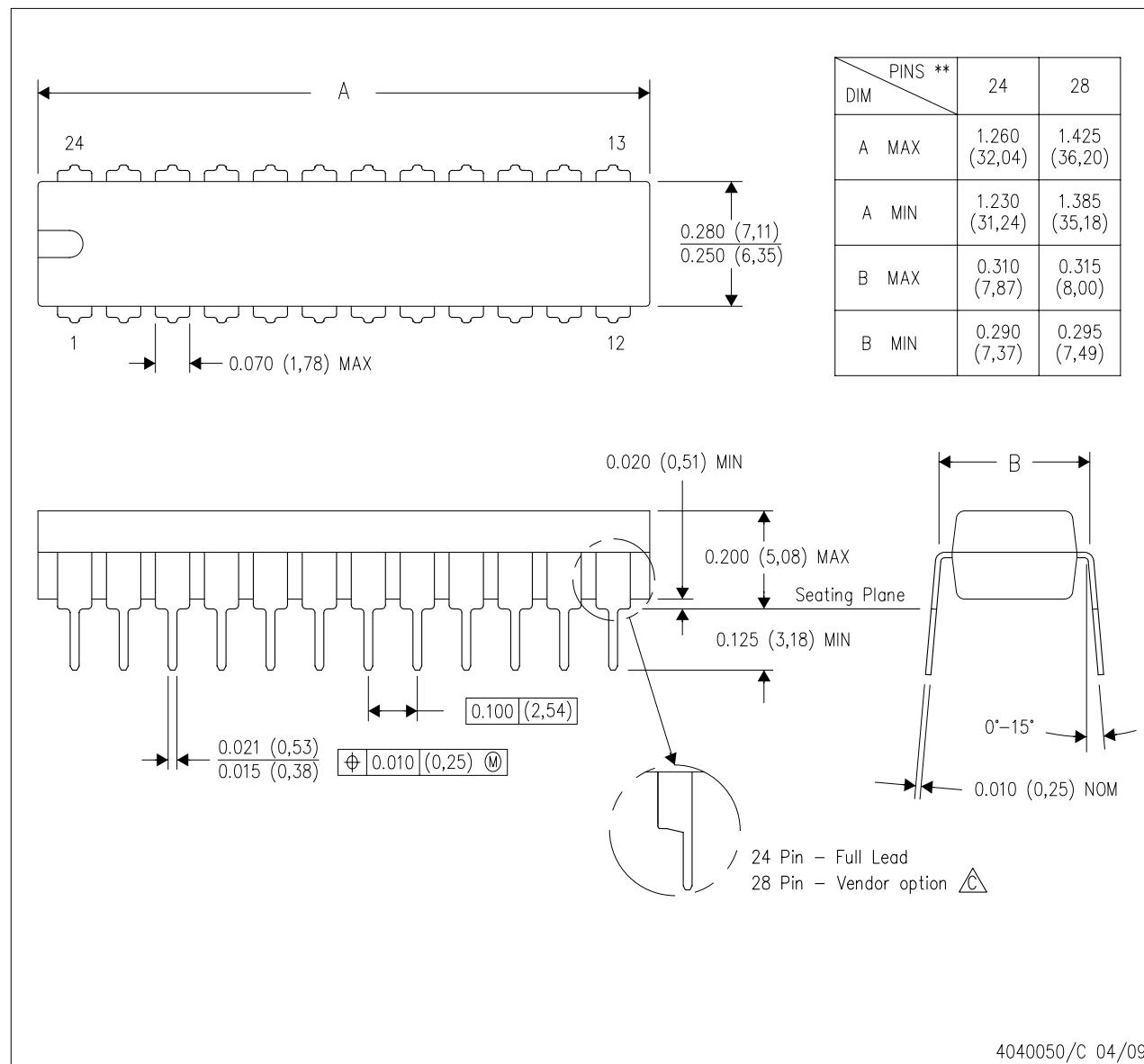
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

MECHANICAL DATA

NT (R-PDIP-T**)

24 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



4040050/C 04/09

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

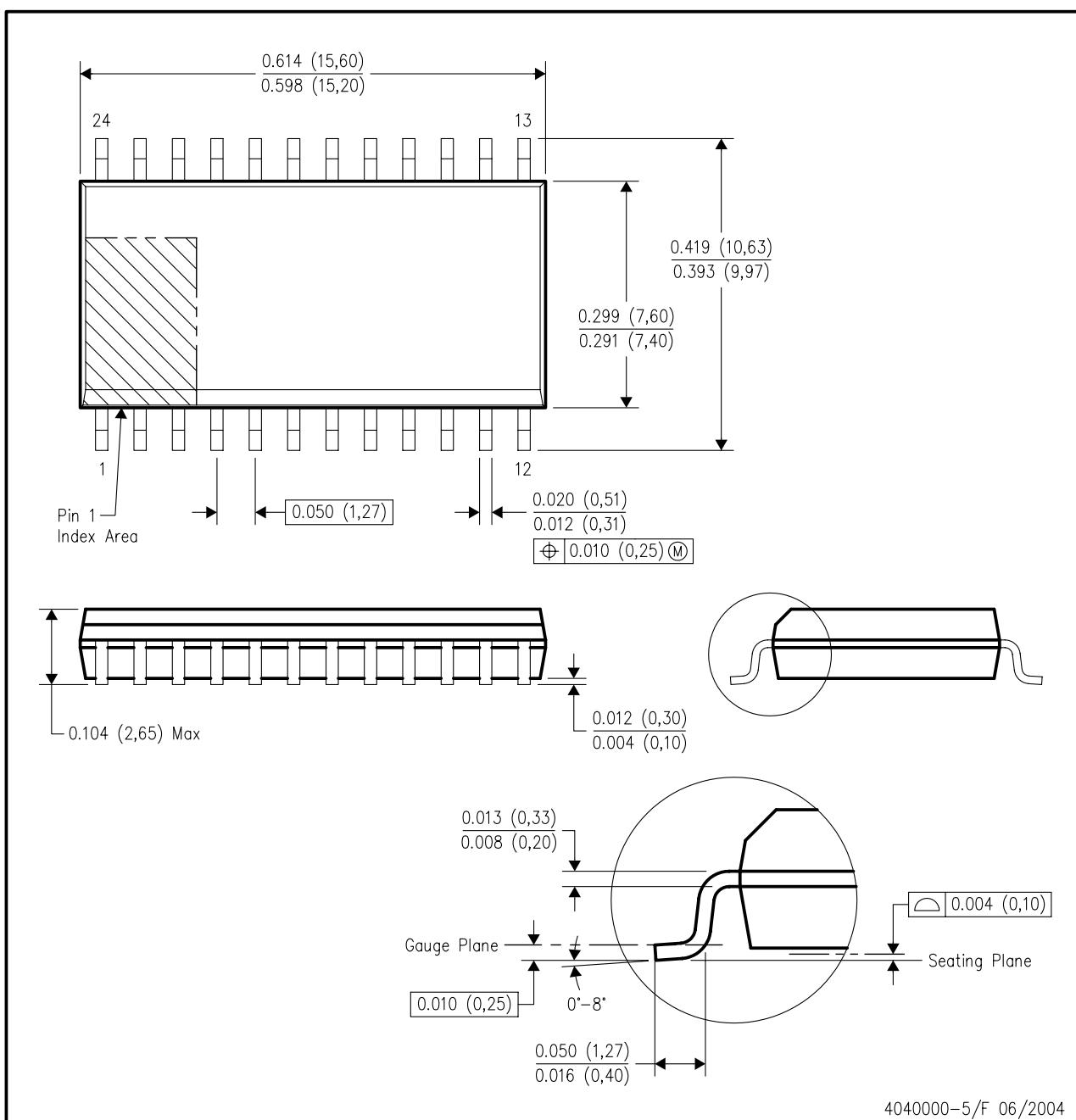
B. This drawing is subject to change without notice.

△ The 28 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-5/F 06/2004

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- D. Falls within JEDEC MS-013 variation AD.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|---|
| 74ACT11374DBLE | OBsolete | SSOP | DB | 24 | TBD | Call TI | Call TI | -40 to 85 | | | |
| 74ACT11374DW | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11374 | Samples |
| 74ACT11374DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11374 | Samples |
| 74ACT11374DWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11374 | Samples |

(1) The marketing status values are defined as follows:

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a " ~ " will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

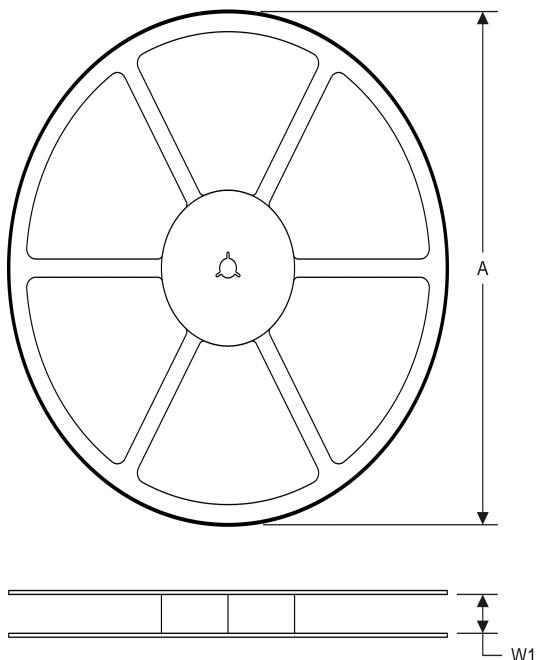
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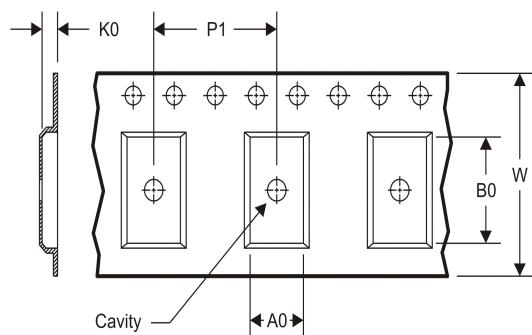
PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



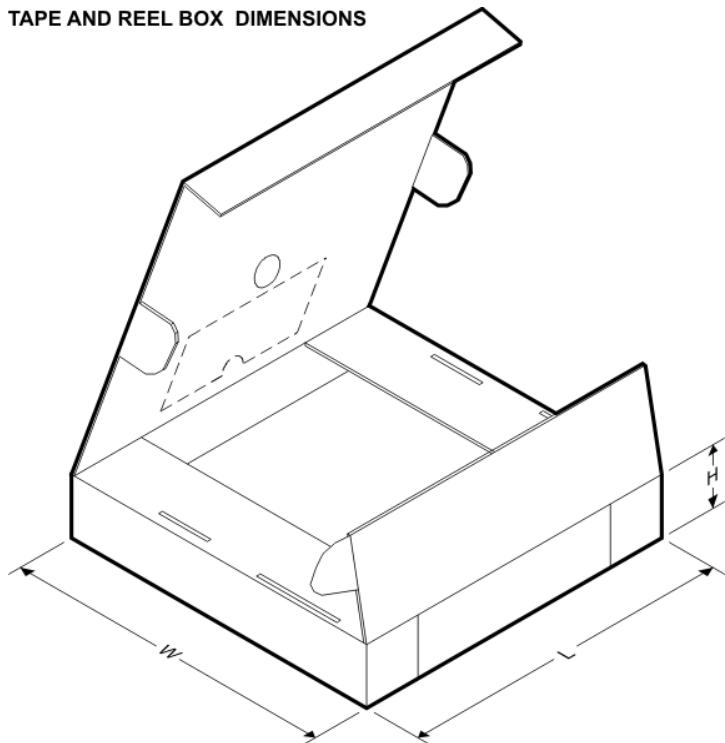
| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| 74ACT11374DWR | SOIC | DW | 24 | 2000 | 330.0 | 24.4 | 10.75 | 15.7 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



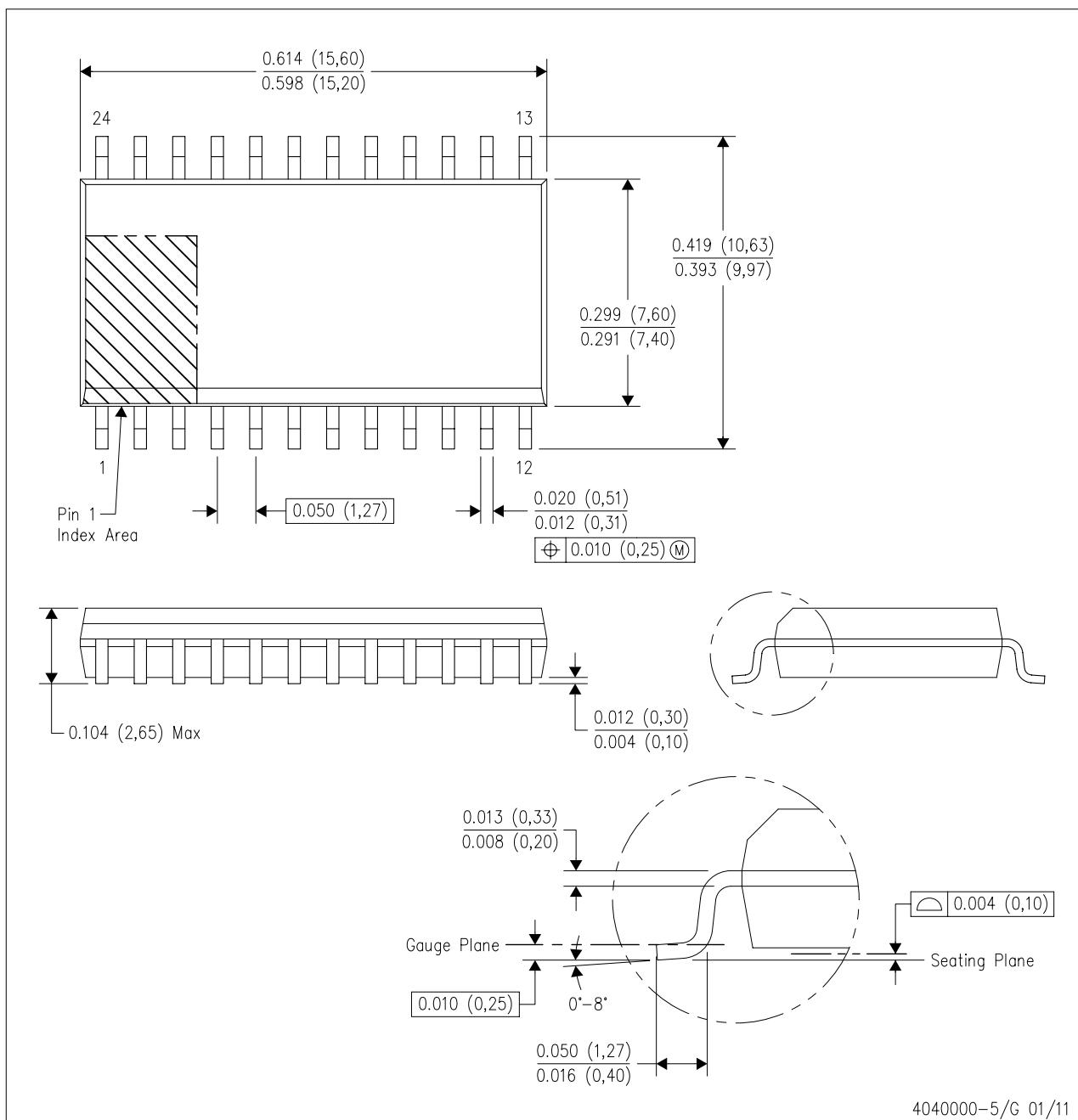
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| 74ACT11374DWR | SOIC | DW | 24 | 2000 | 367.0 | 367.0 | 45.0 |

MECHANICAL DATA

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



4040000-5/G 01/11

NOTES:

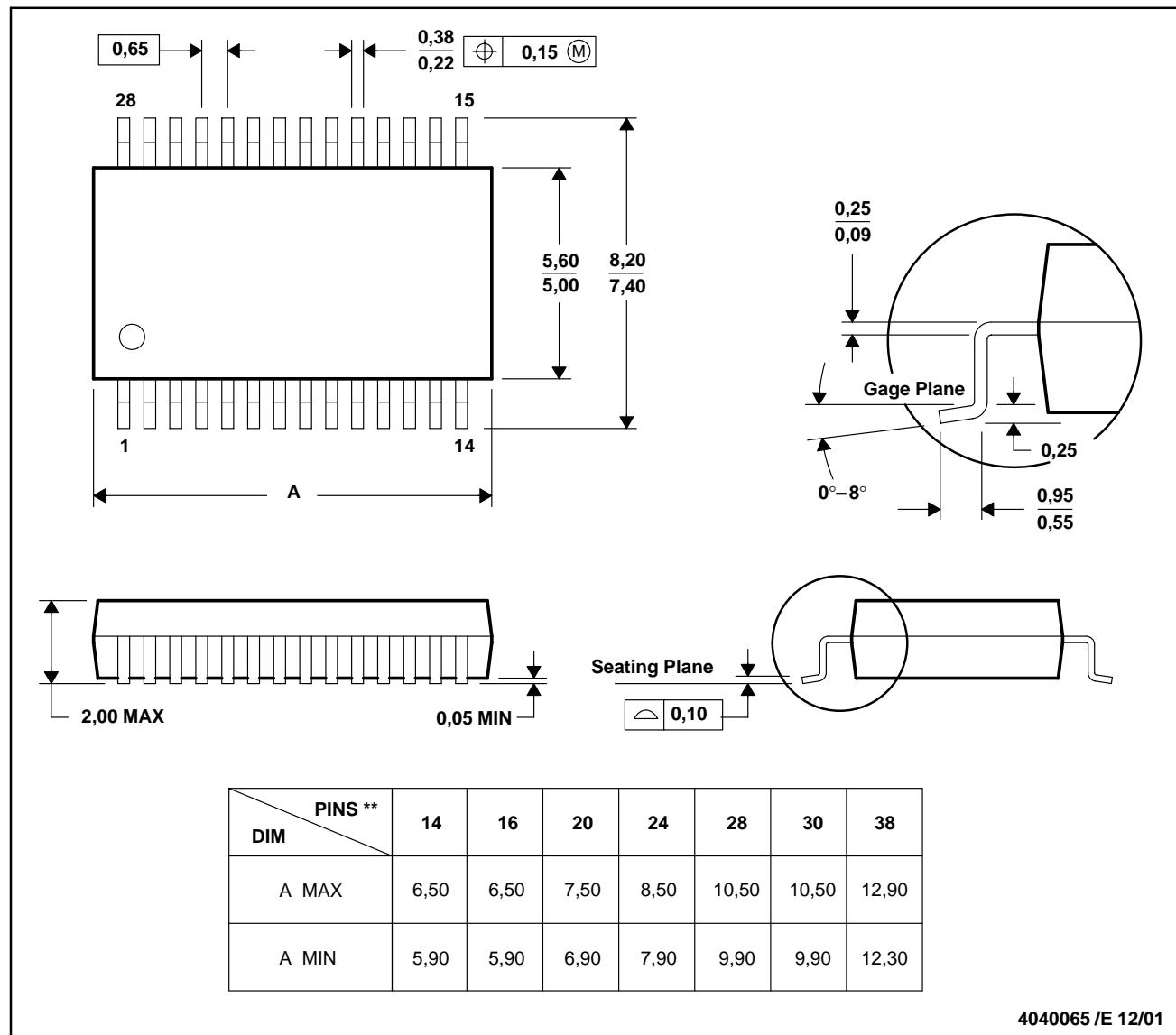
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- D. Falls within JEDEC MS-013 variation AD.

MSS002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)**

28 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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